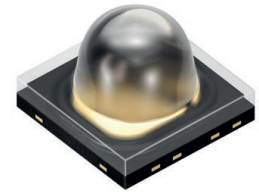


SFH 4717AS

OSLON® Black

OSLON Black Series (850 nm) - 50°



Applications

- 3D Sensing
- Access Control (IRIS/Vein Scan, Face Recognition)
- CCTV Surveillance
- Eye Tracking
- Safety and Security, CCTV

Features:

- Package: diffuse silicone
- Corrosion Robustness Class: 3B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- IR lightsource with high efficiency
- Double stack emitter
- Low thermal resistance (Max. 9 K/W)
- Centroid wavelength 850 nm

Ordering Information

Type	Radiant intensity ¹⁾ I_e $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$	Radiant intensity ¹⁾ typ. I_e $I_F = 1 \text{ A}; t_p = 10 \text{ ms}$	Ordering Code
SFH 4717AS	800 ... 1600 mW/sr	1,150 mW/sr	Q65112A1517

Maximum Ratings

$T_A = 25\text{ °C}$

Parameter	Symbol		Values
Operating temperature	T_{op}	min. max.	-40 °C 125 °C
Storage temperature	T_{stg}	min. max.	-40 °C 125 °C
Junction temperature	T_j	max.	145 °C
Forward current	I_F	max.	1500 mA
Surge current $t_p \leq 800\ \mu\text{s}; D = 0.005$	I_{FSM}	max.	3 A
Reverse current ²⁾	I_R	max.	200 mA
Power consumption	P_{tot}	max.	5.8 W
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}	max.	2 kV

For the forward current and power consumption please see “maximum permissible forward current” diagram

Characteristics

$I_F = 1000 \text{ mA}$; $t_p = 10 \text{ ms}$; $T_A = 25 \text{ °C}$

Parameter	Symbol		Values
Peak wavelength	λ_{peak}	typ.	860 nm
Centroid wavelength	$\lambda_{\text{centroid}}$	typ.	850 nm
Spectral bandwidth at 50% $I_{\text{rel,max}}$ (FWHM)	$\Delta\lambda$	typ.	30 nm
Half angle	φ	typ.	25 °
Dimensions of active chip area	L x W	typ.	1 x 1 mm x mm
Rise time (10% / 90%) $I_F = 3 \text{ A}$; $R_L = 50 \text{ }\Omega$	t_r	typ.	12 ns
Fall time (10% / 90%) $I_F = 3 \text{ A}$; $R_L = 50 \text{ }\Omega$	t_f	typ.	15 ns
Forward voltage	V_F	typ. max.	3.15 V 3.5 V
Forward voltage $I_F = 1.5 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$	V_F	typ. max.	3.3 V 3.85 V
Forward voltage $I_F = 3 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$	V_F	typ. max.	3.8 V 4.7 V
Reverse voltage ²⁾ $I_R = 20 \text{ mA}$	V_R	max.	1.2 V
Reverse voltage (ESD device) ²⁾	$V_{\text{RES D}}$	min.	5 V
Radiant intensity ¹⁾ $I_F = 1.5 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$	I_e	typ.	1720 mW/sr
Total radiant flux ³⁾ $I_F = 1 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$	Φ_e	typ.	1340 mW
Total radiant flux ³⁾ $I_F = 1.5 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$	Φ_e	typ.	1990 mW
Temperature coefficient of voltage	TC_V	typ.	-2 mV / K
Temperature coefficient of brightness	TC_I	typ.	-0.3 % / K
Temperature coefficient of wavelength	TC_λ	typ.	0.3 nm / K
Thermal resistance junction solder point real ⁴⁾	R_{thJS}	typ. max.	5.5 K / W 9.0 K / W

Brightness Groups

$T_A = 25\text{ °C}$

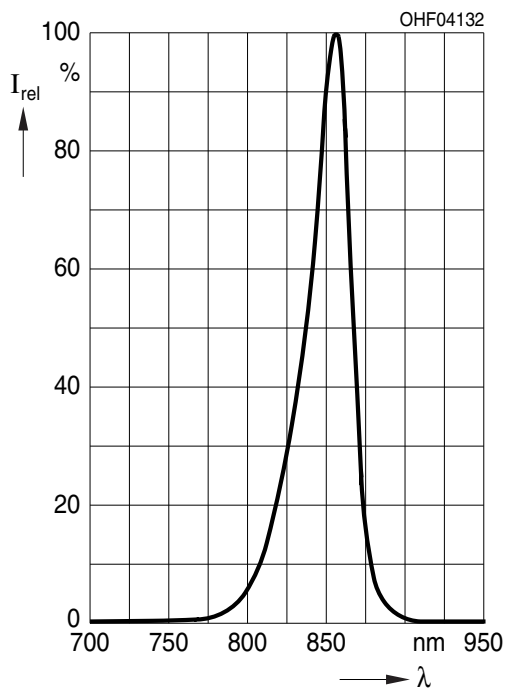
Group	Radiant intensity	Radiant intensity
	$I_F = 1000\text{ mA}; t_p = 10\text{ ms}$ min. I_e	$I_F = 1000\text{ mA}; t_p = 10\text{ ms}$ max. I_e
EB	800 mW/sr	1250 mW/sr
FA	1000 mW/sr	1600 mW/sr

Only one group in one packing unit (variation lower 1.6:1).

The brightness values are measured during a current pulse of typically 10ms, with a tolerance of +/- 12%.

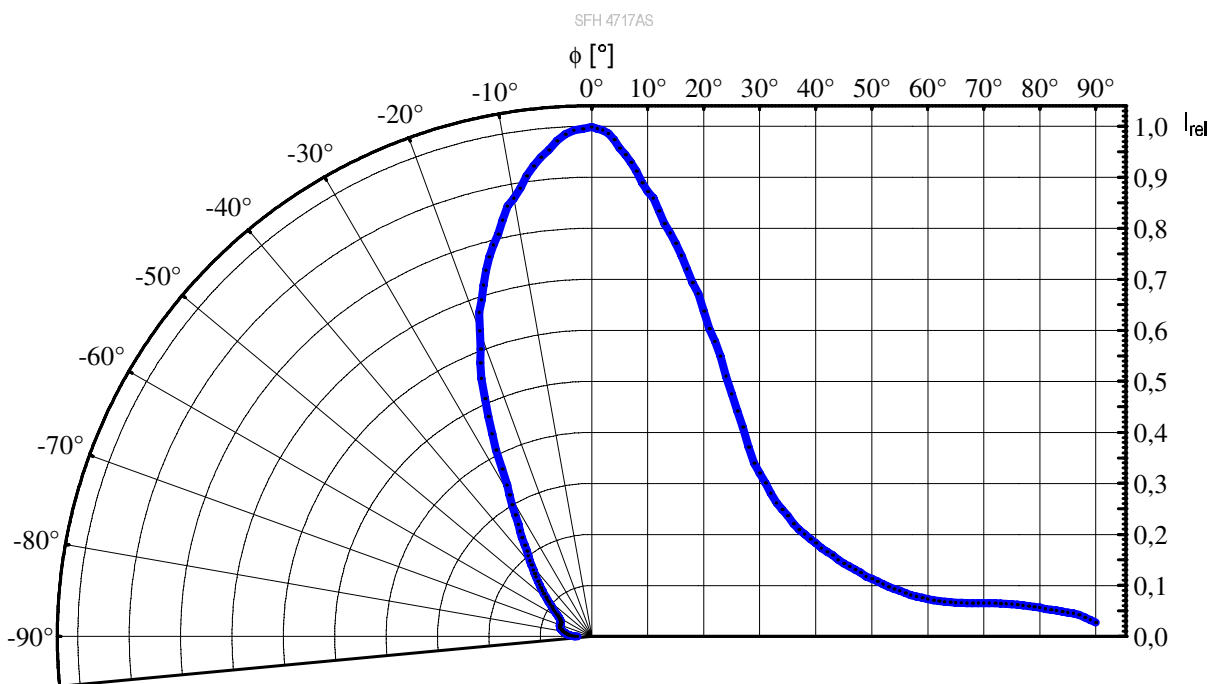
Relative Spectral Emission ^{5), 6)}

$I_{e,rel} = f(\lambda); I_F = 1000\text{ mA}; t_p = 10\text{ ms}$



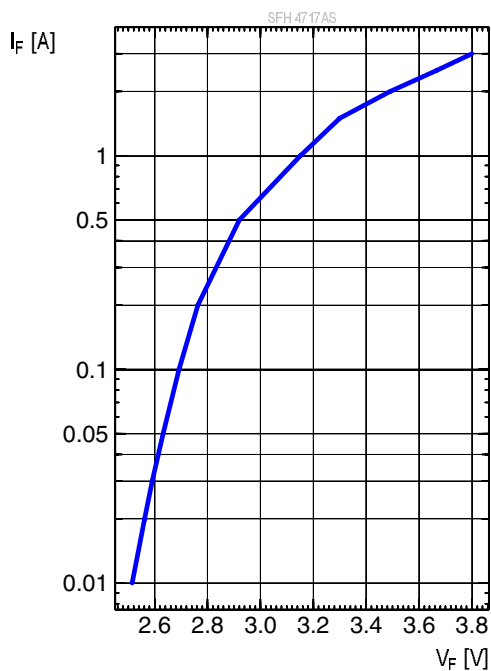
Radiation Characteristics ^{5), 6)}

$$I_{e,rel} = f(\varphi)$$



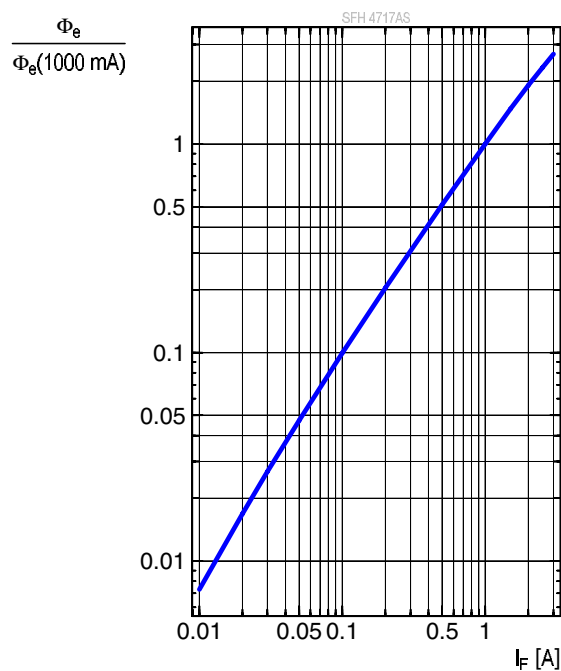
Forward current ^{5), 6)}

$$I_F = f(V_F); \text{ single pulse; } t_p = 100 \mu s$$



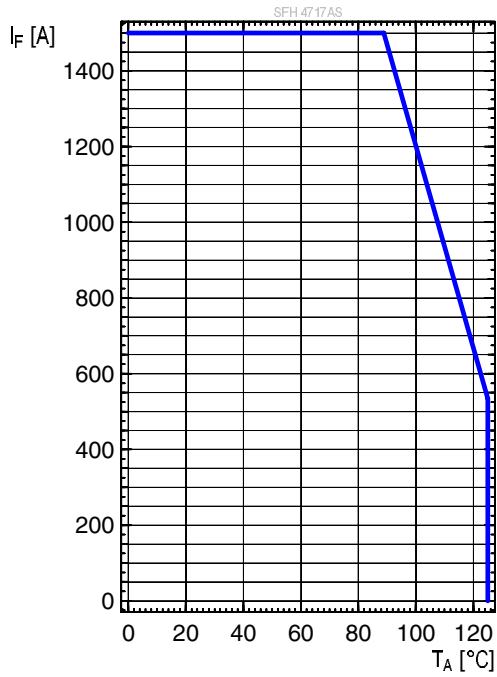
Relative Total Radiant Flux ^{5), 6)}

$$\frac{\Phi_e}{\Phi_e(1000mA)} = f(I_F); \text{ single pulse; } t_p = 100 \mu s$$



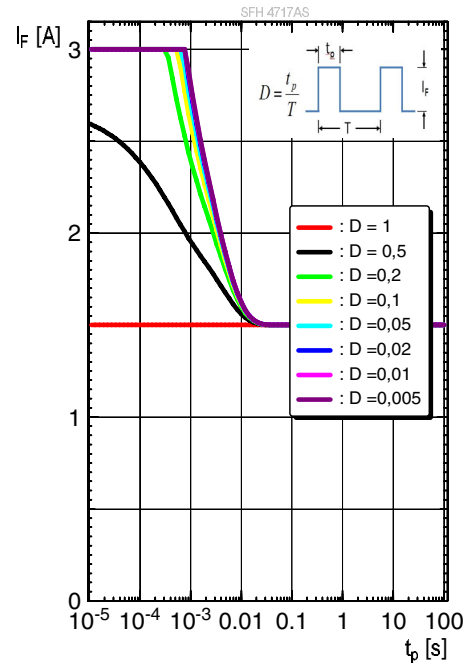
Max. Permissible Forward Current

$I_{F,max} = f(T_S)$; $R_{th_{js}} = 9K / W$; single pulse

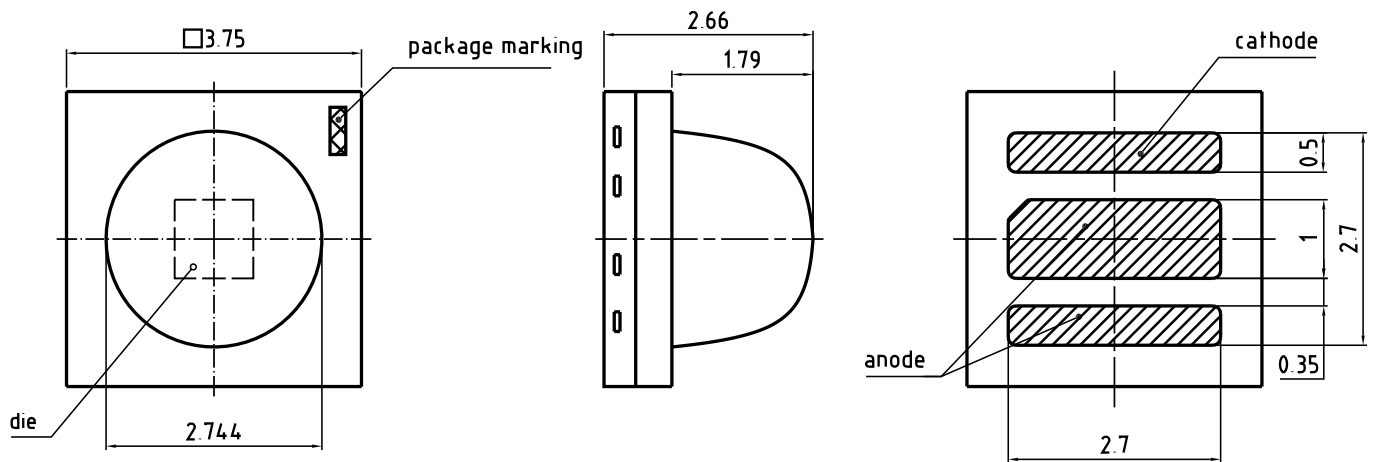


Permissible Pulse Handling Capability

$I_F = f(t_p)$; duty cycle $D =$ parameter; $T_S = 85^\circ C$



Dimensional Drawing ⁷⁾



general tolerance ± 0.1

lead finish Au 

C63062-A4141-A8...-04

Further Information

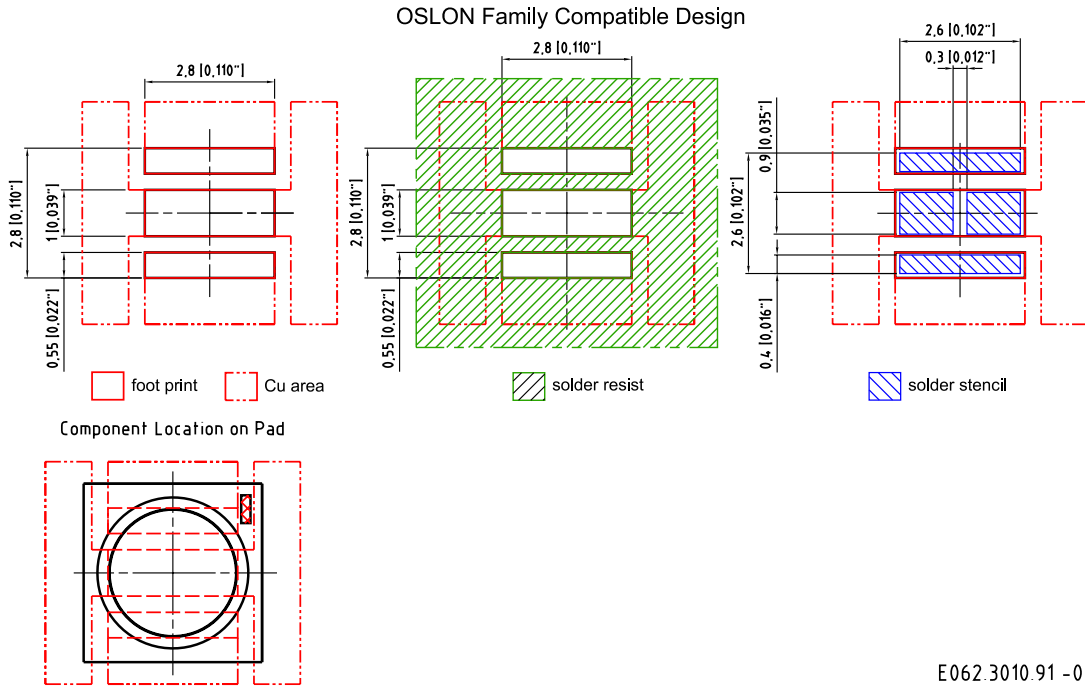
Approximate Weight: 31.0 mg

Package marking: Cathode

Corrosion test: Class: 3B
 Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC 60068-2-43)

ESD advice: The device is protected by ESD device which is connected in parallel to the Chip.

Recommended Solder Pad ⁷⁾

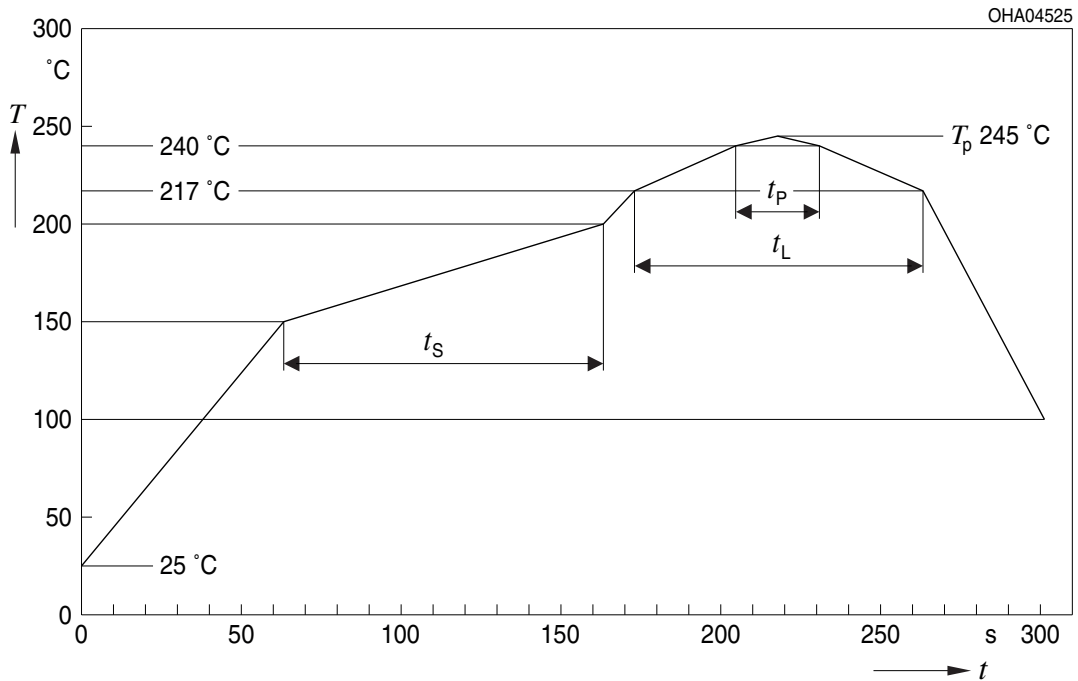


E062.3010.91-05

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

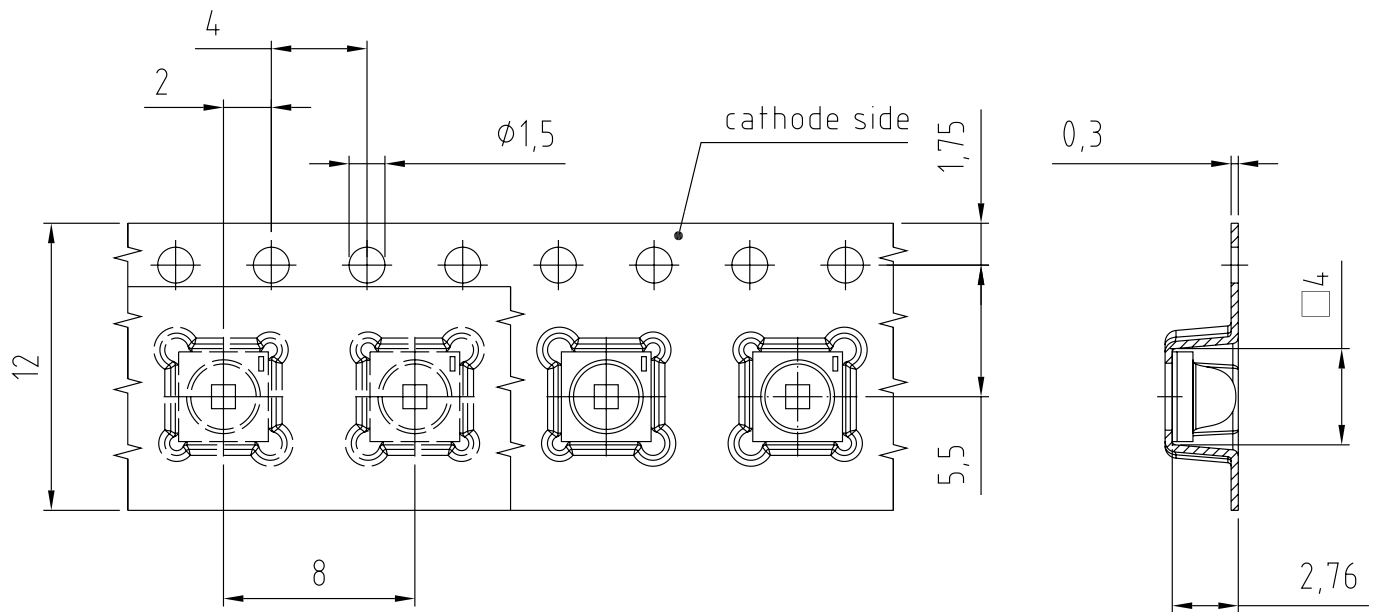


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak ^{*)} T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	260	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	6	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component

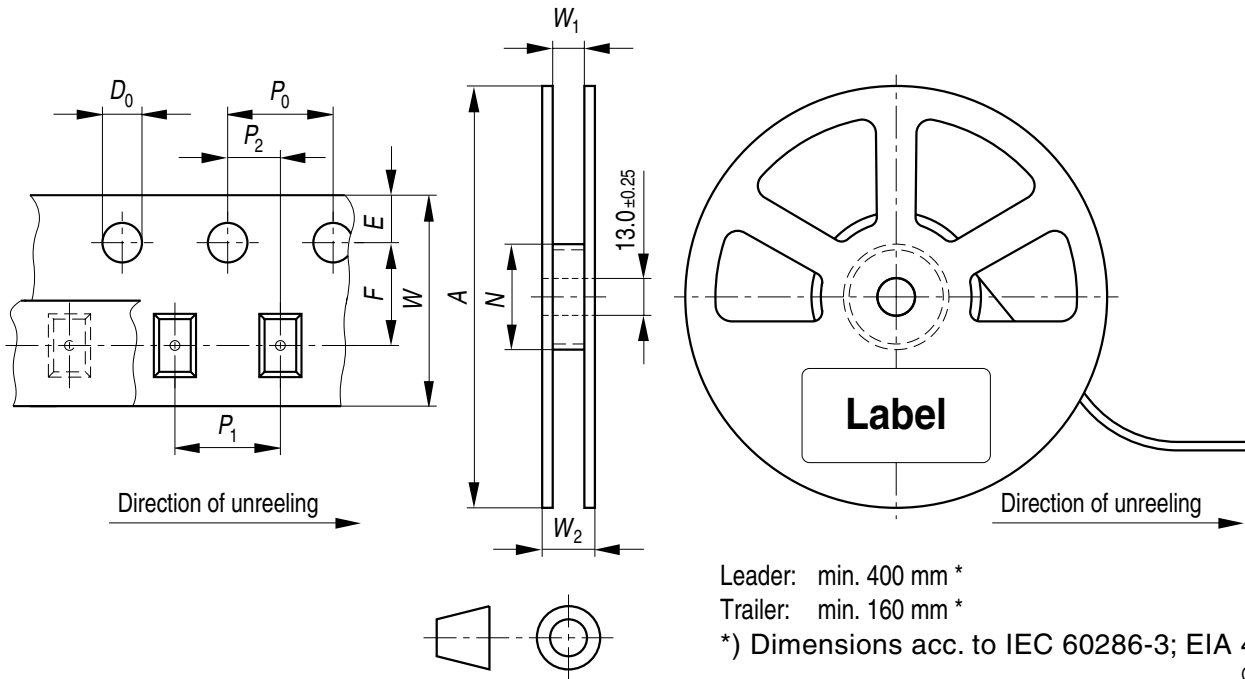
* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping ⁷⁾



C63062-A4141-B10 -01

Tape and Reel ⁸⁾



Reel Dimensions

A	W	N_{min}	W_1	W_{2max}	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	600

Barcode-Product-Label (BPL)

OSRAM Opto Semiconductors LX XXXX BIN1: XX-XX-X-XXX-X

RoHS Compliant

(6P) BATCH NO: 1234567890

(1T) LOT NO: 1234567890 (9D) D/C: 1234

(X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X

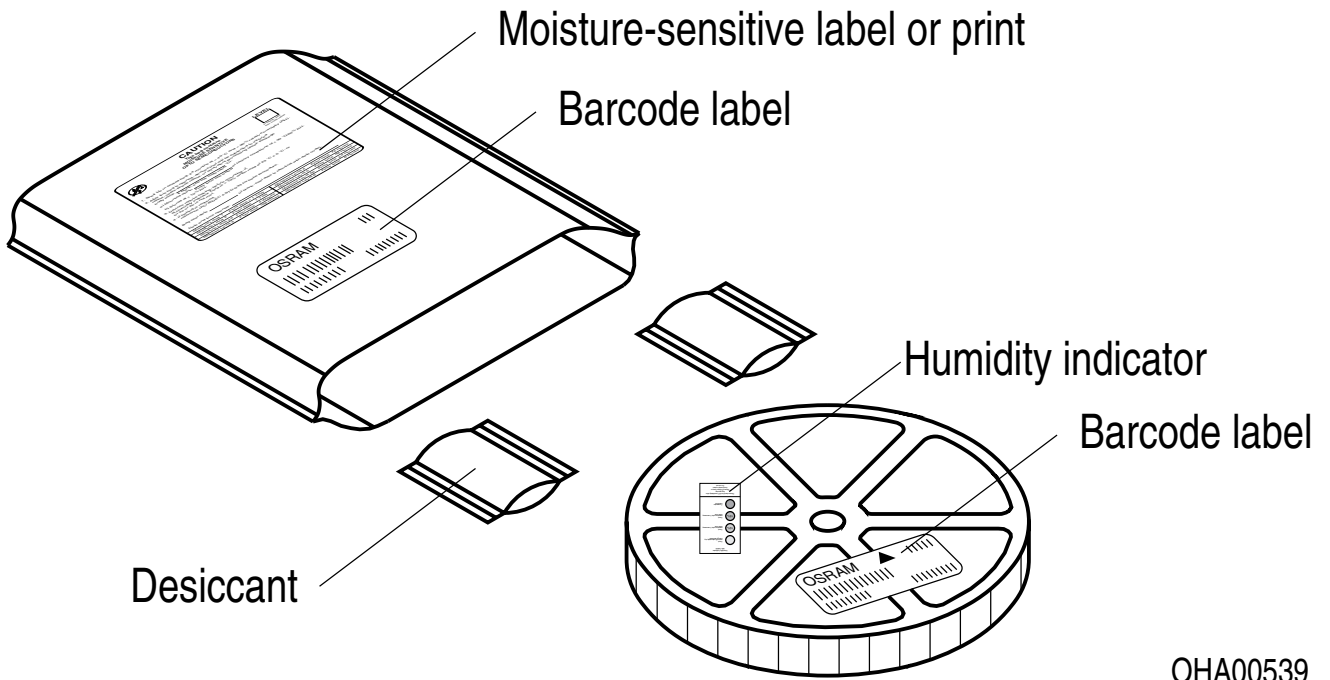
ML Temp ST
X XXX °C X

Pack: RXX
DEMY XXX
X_X123_1234.1234 X

The diagram shows a rectangular label with rounded corners. It contains the OSRAM logo and product name at the top left. To the right are fields for 'LX XXXX' and 'BIN1: XX-XX-X-XXX-X'. Below this is 'RoHS Compliant'. The main body of the label is divided into three horizontal sections, each with a barcode and associated text: (6P) BATCH NO: 1234567890, (1T) LOT NO: 1234567890 (9D) D/C: 1234, and (X) PROD NO: 123456789(Q)QTY: 9999 (G) GROUP: XX-XX-X-X. To the right of the second section is a 'No moisture' symbol (a circle with a diagonal line and three drops) and 'ML Temp ST X XXX °C X'. Below that is 'Pack: RXX', 'DEMY XXX', and 'X_X123_1234.1234 X'. A square QR code is located on the right side of the label.

OHA04563

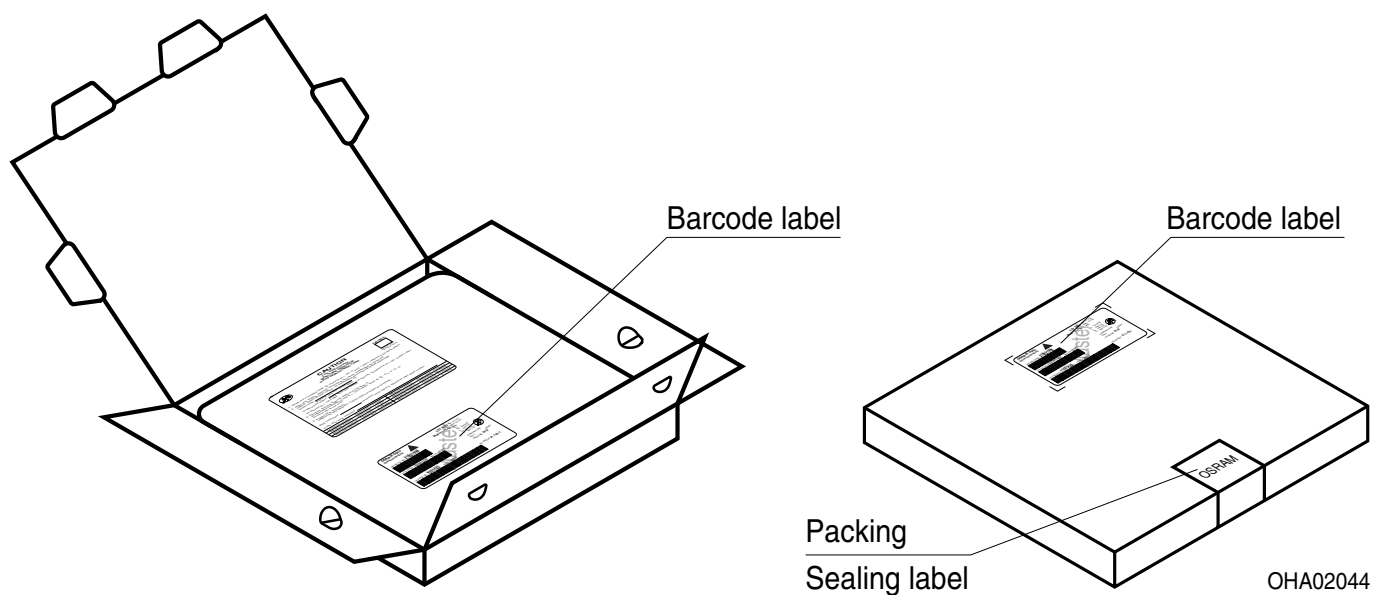
Dry Packing Process and Materials ⁷⁾



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Schematic Transportation Box ⁷⁾



Dimensions of Transportation Box

Width

Length

Height

195 ± 5 mm

195 ± 5 mm

30 ± 5 mm

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

Glossary

- 1) **Radiant intensity:** Measured at a solid angle of $\Omega = 0.01$ sr
- 2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) **Total radiant flux:** Measured with integrating sphere.
- 4) **Thermal resistance:** junction - soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- 5) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 6) **Testing temperature:** TA = 25°C (unless otherwise specified)
- 7) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 8) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.0	2019-09-05	Initial Version

Published by OSRAM Opto Semiconductors GmbH EU RoHS and China RoHS compliant product
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